# MSKSEMI 美森科







TVC



TSS



MOV



GDT



PIFD

## **TVSS5VCES-02GP**

**Product specification** 





## **FEATURES**

• IEC61000-4-2 (ESD) ±30kV (Contact),

±30kV (Air)

• IEC61000-4-4 (EFT) 40A (5/50ηs)

Peak power dissipation: 128W (8/20µs)

Protects one I/O line

Low clamping voltage

Working voltages : 5V

Low leakage current

## **MACHANICAL DATA**

SOD-523 package

Terminals: Tin plated, solderable per

• MIL-STD-750, method 2026

Packaging: Tape and Reel

Reel size: 7 inch

MSL1

## **APPLICATIONS**

High Speed Line :USB1.0/2.0, VGA, DVI, SDI,

Serial and Parallel Ports

Notebooks, Desktops, Servers

Projection TV

Cellular handsets and accessories

Portable instrumentation

Peripherals

## **Reference News**

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
NEW PARTY OF THE P	2	<b>B5</b> ∞
SOD-523		



## **ABSOLUTE MAXIMUM RATING**

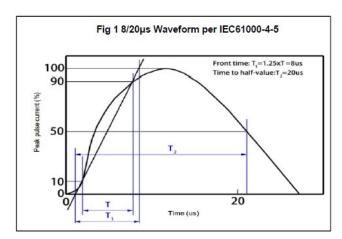
Symbol	Parameter	Value	Units	
V	ESD per IEC 61000-4-2 (Contact)	±30	kV	
V <sub>ESD</sub>	ESD per IEC 61000-4-2 (Air)	±30	KV	
P <sub>PP</sub>	Peak Pulse Power (8/20µs)	128	W	
Торт	Operating Temperature -40~150		$^{\circ}$	
T <sub>STG</sub>	T <sub>STG</sub> Storage Temperature -40~150		$^{\circ}$	

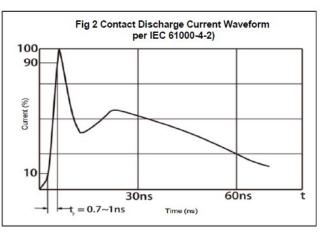
## **ELECTRICAL CHARACTERISTICS (Tamb=25℃)**

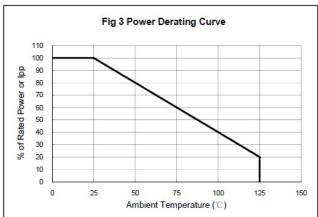
Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V <sub>RWM</sub>	Reverse Working Voltage				5.0	V
$V_{BR}$	Reverse Breakdown Voltage	I <sub>T</sub> = 1mA	5.6		9.0	V
<b>I</b> R	Reverse Leakage Current	V <sub>RWM</sub> = 5V			0.1	μΑ
Vc	Clamping Voltage	$I_{PP} = 5A, t_p = 8/20 \mu s$			11.6	V
Vc	Clamping Voltage	$I_{PPmax} = 8A , t_p = 8/20 \mu s$			16.0	V
Сл	Junction Capacitance	V <sub>R</sub> = 0V, f = 1MHz		10	15	pF

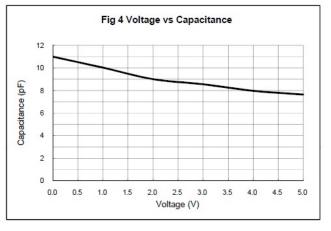


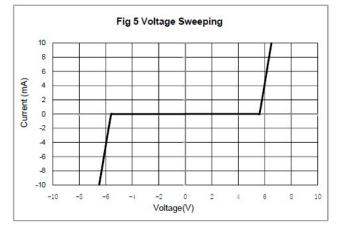
## **ELECTRICAL CHARACTERISTICS CURVE**

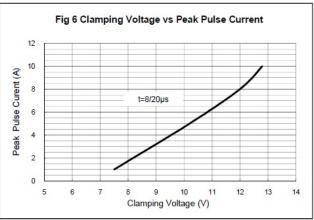






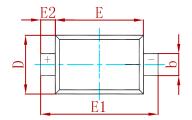


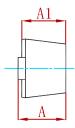


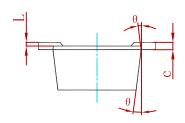




## **PACKAGE MECHANICAL DATA**

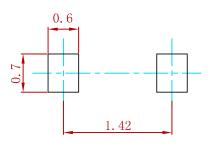






Symbol	Dimensions In Millimeters		Dimensions In Inches	
Symbol	Min	Max	Min	Max
Α	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
С	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008	3 REF
L	0.010	0.070	0.001	0.003
θ	7° REF		7° F	REF

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
TVSS5VCES-02GP	SOD-523	3000



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